

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. **(Currently Amended)** A substrate processing method including:
a first step of injecting droplets formed by mixing an alkaline solution and gas ~~with each other~~ to a surface of a substrate; and
a second step of injecting droplets formed by mixing an acid solution and gas ~~with each other~~ to the surface of said substrate after said first step, wherein
said alkaline solution and said acid solution are at an ordinary temperature.
2. **(Original)** The substrate processing method according to claim 1, wherein
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.
3. **(Original)** The substrate processing method according to claim 2, wherein
said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.
4. **(Currently Amended)** A substrate processing method including:
a first step of supplying an alkaline solution imparted with megasonic vibrations to a surface of a substrate; and
a second step of supplying an acid solution to the surface of said substrate after said first step, wherein
said alkaline solution and said acid solution are at an ordinary temperature.
5. **(Original)** The substrate processing method according to claim 4, wherein
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

6. **(Original)** The substrate processing method according to claim 5, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.
7. **(Currently Amended)** A substrate processing method including:
a first step of supplying an alkaline solution to a surface of a substrate;
a second step of supplying an acid solution to the surface of said substrate after said first step; and
a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein
at least either supply of said acid solution in said second step or supply of said alkaline solution in said third step comprises injection of droplets formed by mixing said solution with gas.
8. **(Original)** The substrate processing method according to claim 7, wherein only supply of said alkaline solution in said first step and said third step is injection of droplets formed by mixing said alkaline solution with gas.
9. **(Currently Amended)** The substrate processing ~~apparatus~~ method according to claim 8, wherein
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.
10. **(Original)** The substrate processing method according to claim 9, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.
11. **(Currently Amended)** A substrate processing method including:
a first step of supplying an alkaline solution to a surface of a substrate;
a second step of supplying an acid solution to the surface of said substrate after said first step; and

a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein

at least either supply of said acid solution in said second step or supply of said alkaline solution in said third step is ~~supply~~ comprising supplying of said solution ~~imparted with~~ subjected to megasonic vibrations.

12. (Currently Amended) The substrate processing method according to claim 11, wherein

only the supply of said alkaline solution in said first step and said third step is performed with ~~supply of~~ said alkaline solution ~~imparted with~~ subjected to megasonic vibrations.

13. (Currently Amended) The substrate processing method ~~apparatus~~ according to claim 12, wherein

said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

14. (Original) The substrate processing method according to claim 13, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

15. - 18. (Canceled)

19. (New) A substrate processing method according to claim 1, wherein said alkaline solution has a pH value of at least 11 and less than 13.

20. (New) The substrate processing method according to claim 4, wherein said alkaline solution has a pH value of at least 11 and less than 13.

21. (New) The substrate processing method according to claim 7, said alkaline solution and said acid solution being at an ordinary temperature.

22. (New) The substrate processing method according to claim 21, wherein said alkaline solution has a pH value of at least 11 and less than 13.

23. (New) The substrate processing method according to claim 11, said alkaline solution and said acid solution being at an ordinary temperature.

24. (New) The substrate processing method according to claim 23, wherein said alkaline solution has a pH value of at least 11 and less than 13.